SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

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- Samsung P/N: CL21C103JBFNFNE
- Description : CAP, \(10 \mathrm{nF}, 50 \mathrm{~V}, \pm 5 \%, \mathrm{COG}, 0805\)
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## A. Samsung Part Number

$\begin{array}{ll}\text { CL } & \underline{21} \\ \text { (2) }\end{array}$
$\begin{array}{ll}\text { C } & 103 \\ (4)\end{array}$
J $\quad$ B
F N
$\begin{array}{lll}\text { F } & \underline{N} & \underline{E} \\ \text { (9) } & \text { (10) } & \text { (11) }\end{array}$

| (1) Series | Samsung Multi-layer Ceramic Capacitor |  |  | W: | $1.25 \pm 0.10 \mathrm{~mm}$ |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| (2) Size | 0805 (inch code) | L: 2.00 | $\pm 0.10 \mathrm{~mm}$ |  |  |  |
| (3) Dielectric | COG | (8) | Inner electrode |  | Ni |  |
| (4) Capacitance | 10 nF |  | Termination |  | Cu |  |
| (5) Capacitance | $\pm 5 \%$ |  | Plating |  | Sn 100\% | (Pb Free) |
| tolerance |  | (9) | Product |  | Product for | VER applica |
| (6) Rated Voltage | 50 V | (10) | Special |  | Reserved | ure use |
| (7) Thickness | $1.25 \pm 0.10 \mathrm{~mm}$ | (11) | Packaging |  | Embosse | 7" reel |

B. Structure and dimension


| Samsung P/N <br> (Lead Free) | Dimension(mm) |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
|  | L | W | T | BW |
| CL21C103JBFNFNE | $2.00 \pm 0.10$ | $1.25 \pm 0.10$ | $1.25 \pm 0.10$ | $0.50+0.20 /-0.30$ |


|  | Performance | Test condition |
| :---: | :---: | :---: |
| Capacitance | Within specified tolerance | $1 \mathrm{kHz} \pm 10 \% / 0.5 \sim 5 \mathrm{Vrms}$ |
| Q | 1,000 min |  |
| Insulation Resistance | 10,000 Mohm or 500 Mohm $\times \mu \mathrm{F}$ Whichever is smaller | Rated Voltage 60~120 sec. |
| Appearance | No abnormal exterior appearance | Microscop (X10) |
| Withstanding Voltage | No dielectric breakdown or mechanical breakdown | $300 \%$ of the rated voltage |
| Temperature Characteristics | COG (From $-55^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$, Capacitance change | uld be within $\pm 30 \mathrm{PPM} /{ }^{\circ} \mathrm{C}$ ) |
| Adhesive Strength of Termination | No peeling shall be occur on the terminal electrode | $500 \mathrm{~g} \times \mathrm{F}$, for $10 \pm 1 \mathrm{sec}$. |
| Bending Strength | Capacitance change : <br> within $\pm 5 \%$ or $\pm 0.5 \mathrm{pF}$ whichever is larger | Bending to the limit (1mm) with $1.0 \mathrm{~mm} / \mathrm{sec}$. |
| Solderability | More than $75 \%$ of terminal surface is to be soldered newly | $\begin{aligned} & \text { SnAg3.0Cu0.5 solder } \\ & 245 \pm 5^{\circ} \mathrm{C}, 3 \pm 0.3 \mathrm{sec} . \\ & \text { (preheating : 80~120 }{ }^{\circ} \mathrm{C} \text { for } 10 \sim 30 \mathrm{sec} \text {.) } \end{aligned}$ |
| Resistance to Soldering heat | Capacitance change : within $\pm 2.5 \%$ or $\pm 0.25 \mathrm{pF}$ whichever is larger Tan $\delta$, IR : initial spec. | Solder pot : $270 \pm 5^{\circ} \mathrm{C}, 10 \pm 1 \mathrm{sec}$. |
| Vibration Test | Capacitance change : within $\pm 2.5 \%$ or $\pm 0.25 \mathrm{pF}$ whichever is larger Tan $\delta$, IR : initial spec. | Amplitude : 1.5 mm <br> From 10 Hz to 55 Hz (return: 1 min .) <br> 2hours ' 3 direction ( $x, y, z$ ) |
| Moisture Resistance | ```Capacitance change : within \(\pm 7.5 \%\) or \(\pm 0.75 \mathrm{pF}\) whichever is larger Q: \(\quad 200 \mathrm{~min}\) IR: \(\quad 500 \mathrm{Mohm}\) or \(25 \mathrm{Mohm} \times \mu \mathrm{F}\) Whichever is smaller``` | With rated voltage $40 \pm 2^{\circ} \mathrm{C}, 90 \sim 95 \% \mathrm{RH}, 500+12 /-0 \mathrm{hrs}$ |
| High Temperature Resistance | Capacitance change : <br> within $\pm 3 \%$ or $\pm 0.3 \mathrm{pF}$ whichever is larger <br> Q: $\quad 350 \mathrm{~min}$ <br> IR: $\quad 1,000$ Mohm or $50 \mathrm{Mohm} \times \mu \mathrm{F}$ <br> Whichever is smaller | With 200\% of the rated voltage Max. operating temperature 1000+48/-Ohrs |
| Temperature Cycling | Capacitance change : within $\pm 2.5 \%$ or $\pm 0.25 \mathrm{pF}$ whichever is larger Tan $\delta$, IR : initial spec. | 1 cycle condition <br> Min. operating temperature $\rightarrow 25^{\circ} \mathrm{C}$ $\rightarrow \quad \text { Max. operating temperature } \quad \rightarrow \quad 25^{\circ} \mathrm{C}$ <br> 5 cycle test |

※ The reliability test condition can be replaced by the corresponding accelerated test condition.

## D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : $260+0 /-5^{\circ} \mathrm{C}$, 10 sec . Max )

Product specifications included in the specifications are effective as of March 1, 2013.
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